Technical Information







Solvent based flux remover for manual PCB defluxing after rework

VIGON® EFM is a precision cleaning agent designed to remove flux residues from electronic assemblies in manual applications. This product can also be used in explosion-proof spray-in-air equipment. VIGON® EFM is a mixture of halogen-free, organic solvents. It dries fast and residue-free. VIGON® EFM is non-corrosive and compatible with most polymers.

Areas of Application: Manual PCB Cleaning

| Recommended Solder Paste Applications: | Additional Product Information |
|---|---------------------------------|
| No Clean (NC) | Material Compatibility Overview |
| Rosin Mildly Activated (RMA) | Malerial Compalibility Overview |
| Rosin (R) | Safahi Data Shaat |
| Rosin Activated (RA) | Safety Data Sheet |
| Applies to leaded and lead-free solder pastes and liquid fluxes | |

Key Benefits

- Especially suitable for removal of rosin and resin-based flux residues.
- Dries fast and residue-free.
- Easy to use, for both manual and automated cleaning in explosion-proof equipment.
- Suitable as a cleaning and rinsing agent.

Process Steps

| Cleaning Process | Parts | 1. Cleaning | 2. Rinsing | 3. Drying |
|-----------------------------------|-------|-------------|------------|--|
| Manual Cleaning | PCBs | VIGON® EFM | VIGON® EFM | Compressed air or open-air evaporation |
| Spray-in-air (explosion-proof) | PCBs | VIGON® EFM | VIGON® EFM | Compressed air or open-air evaporation |

Please refer to the Material Compatibility Overview prior to cleaning plastics.

Technical Information



Technical Data: VIGON® EFM

| | | Liquid | Aerosol |
|---------------------------|--------------------------------|----------------------|---------------------|
| Density | (g/cm³) at 20°C/68°F | 0.72 | Not Determined |
| Surface tension | (mN/m) at 25°C/77°F | 18.6 | - |
| Boiling point | °C/°F | 78 – 120 / 172 – 248 | -44 / -47 |
| Flash point | °C/°F | -12 / 10 | -97 / -143 |
| pH value | 10g/l H₂O | Neutral | Neutral |
| Vapor pressure | (mbar) at 20°C/68°F | Approx. 77 | 8300 |
| Cleaning temperature | °C/°F | Ambient Temperature | Ambient Temperature |
| Solubility in water | | Not Soluble | Not Soluble |
| Application concentration | Ready to Use | Pure | _ |
| HMIS Rating | Health-Flammability-Reactivity | 1 – 3 – 0 | 1 – 4 – 0 |

Product Features & Cleaning Standards



Extensively tested and suitable for cleaning of lead-free solder pastes



100% compliance with EU guidelines (RoHS 1, 2 & 3, WEEE)



Product is free of any critical substances according to SIN & SVHC lists

Environmental, Health & Safety Regulations

- Biodegradable, highly flammable cleaning medium.
- Formulated free of any halogenated compounds.
- Refer to the SDS for specific handling precautions and instructions.

Availability & Storage

| 300 mL (Aerosol) | ✓ |
|---------------------|----------|
| 945 mL (Liquid) | ✓ |
| 18 Liter | ✓ |
| 200 Liter | ✓ |

- Available as concentrate
- Store VIGON® EFM in the original container at a temperature between 5 – 30°C / 41 – 86°F.
- The product has a minimum shelf life of 5 years in factory sealed containers.



Contact ZESTRON's Application Engineering Team for more information or trials: Phone: +1 (703) 393-9880 Email: infousa@zestron.com



